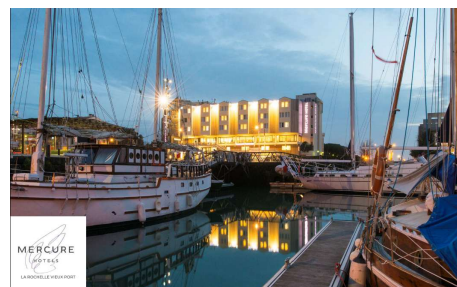


CALL FOR ABSTRACTS



**19th European Advanced Technology
Workshop
ON MICROPACKAGING AND
THERMAL MANAGEMENT
LA ROCHELLE
25th & 26th MARCH 2026**



Conference Chairmen: Jean-Yves SOULIER (Safran Data Systems)
Bruno LEVRIER (Bruno Levrier Expertises)
Jean-Pierre FRADIN (ICAM Toulouse)

Technical Program Committee:

Mohamad ABO RAS (BERLINER NANOTEST)	Boguslaw WIECEK (Technical University of Lodz)
Dave SAUMS (DS & A LLC)	Thomas HARDER (ECPE)
Raphael SOMMET (XLIM Université de Limoges)	Sandrine FENEYROU (Safran Data Systems)
Vincent AYEL (CNRS-ISAE ENSMA-Université de Poitiers)	

We are pleased to open the call for papers of the 19th Advanced Technology Workshop on Micropackaging and Thermal Management that will be held in **La Rochelle on March 25th and 26th, 2026**. This yearly conference has grown year after year by the number of presented papers and attendees.

Be part of a successful 2026 edition and be sure to submit your abstract on time. The workshop sessions will include the following topics. Papers are invited in following areas:

- **Cooling solutions for microelectronics packaging,**
- **Heat conductive materials at chip, board, sub-system and system levels,**
- **Advances in PCBs for thermal management, PCB embedded components included,**
- **Heatsinks, heat pipes and change phase materials,**
- **Liquid and phase change cooling,**
- **Thermal modeling and simulation, Machine Learning and AI optimization,**
- **Innovative cooling solutions,**
- **Thermal management of optoelectronics components (LEDs, IR sensors...),**
- **Overviews or examples of products, systems cooling, power electronics, automotive transport,**
- **Temperature-related or thermal cycles-related reliability of electronic components.**

Speakers will submit 200-300 words abstract detailing their presentation (20 minutes + 5 minutes for questions), no later than **10th, January 2026**.

Speakers pay a reduced registration fee (including MERCURE hotel accommodation for 2 nights and meals) and are also requested to attend the entire workshop to maximize opportunities of exchanging with other attendees and exhibitors.

Notification of acceptance by the Technical Committee: 20th, January 2026.

After notification of acceptance, you commit to attend the workshop or delegate someone else.

Please respond to IMAPS by e-mail: **imaps.france@orange.fr**

International Microelectronics Assembly and Packaging Society –France 17 rue de l'Amiral Hamelin 75016 Paris